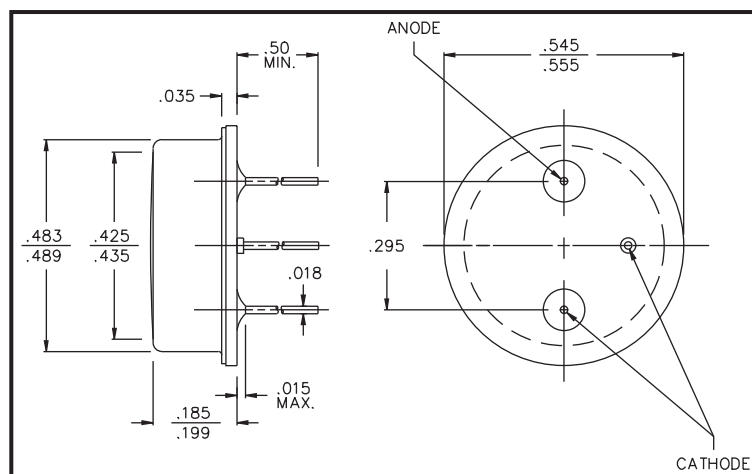


**FEATURES**

- TO-8 hermetic package
- Optimized die size for maximum signal
- Low capacitance

**ELECTRO-OPTICAL CHARACTERISTICS AT 25°C**

PARAMETERS	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Active Area	9.91mm x 4.28mm		42		mm ²
Responsivity, $\mathcal{R}$	@ 632nm	0.35	0.40		A/W
Dark Current, I_{dr}	$V_R = 10V$		11	25	nA
Reverse Breakdown Voltage, V_R	$I_R = 10A$	25	60		Volts
Capacitance, C	$V_R = 10V$		85		pF
Rise Time	$V_R = 10V$		30		nsec
Series Resistance	$V_f = 1V$		35	100	Ohms

THERMAL PARAMETERS

Storage and Operating Temperature Range	-55°C TO 100°C
Maximum Junction Temperature	100°C
Lead Soldering Temperature ¹	260°

¹ 1/16" from case for 10 seconds.

